Surface Mount Schottky Power Rectifier

SMA Power Surface Mount Package

... employing the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes. Typical applications are ac/dc and dc-dc converters, reverse battery protection, and "Oring" of multiple supply voltages and any other application where performance and size are critical.

- Low IR, Extends Battery Life
- 1st in the Market Place with a 10 VR Schottky Rectifier
- Compact Package with J–Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Optimized for Low Leakage Current

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL94, VO at 1/8"
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Ratings: Machine Model = C
 - Human Body Model = 3B
- Available in 12 mm Tape, 5000 Units per 13 inch Reel

MAXIMUM RATINGS

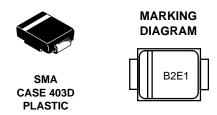
Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	10	V
Average Rectified Forward Current (At Rated V _R , T _C = 125°C)	IO	2.0	A
Non–Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	150	A
Storage/Operating Case Temperature	T _{stg} , T _C	65 to +150	°C
Operating Junction Temperature	Тј	–65 to +150	°C
Voltage Rate of Change (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/μs



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SCHOTTKY BARRIER RECTIFIER 2 AMPERES 10 VOLTS



B2E1 = Device Code

ORDERING INFORMATION

Device	Package	Shipping
MBRA210ET3	SMA	5000/Tape & Reel

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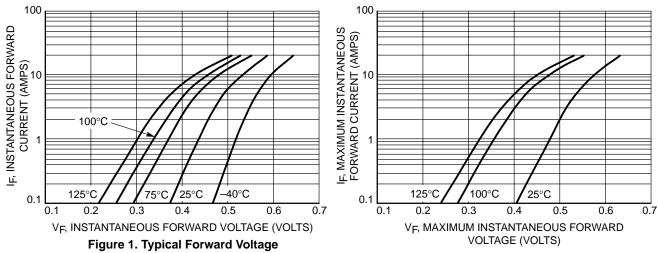
THERMAL CHARACTERISTICS

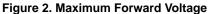
Characteristic	Symbol	Min Pad	1 Inch Pad	Unit
Thermal Resistance – Junction–to–Lead (Note 1)	R _{θJL}	22	15	°C/W
Thermal Resistance – Junction–to–Ambient (Note 1)	R _{θJA}	150	81	

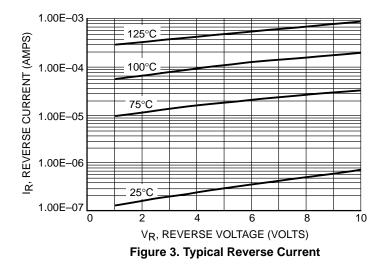
ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2)	V _F	T _J = 25°C	T _J = 100°C	V
(I _F = 0.1 A) (I _F = 1.0 A) (I _F = 2.0 A)		0.405 0.480 0.500	0.275 0.355 0.385	
Maximum Instantaneous Reverse Current	I _R	Tj = 25°C	T _J = 100°C	μΑ
(V _R = 10 V) (V _R = 5.0 V)		15 50	200 500	

Mounted on a 3" square FR4 PC Board with min. pads or 1" square copper heat spreader.
Pulse Test: Pulse Width ≤ 250 µs, Duty Cycle ≤ 2%.







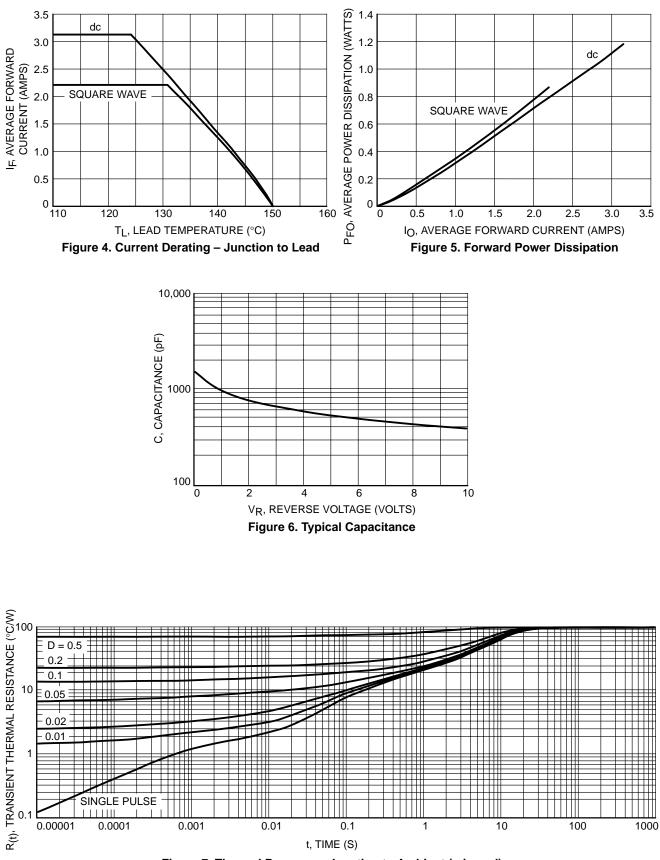


Figure 7. Thermal Response, Junction to Ambient (min pad)

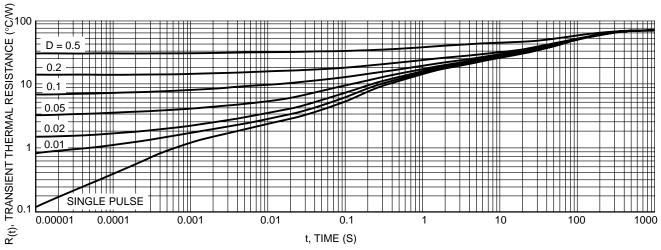
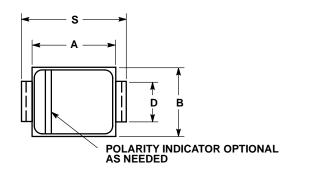


Figure 8. Thermal Response, Junction to Ambient (1 inch pad)

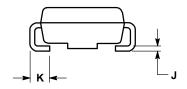
PACKAGE DIMENSIONS

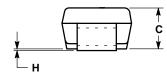
SMA CASE 403D-02 ISSUE A

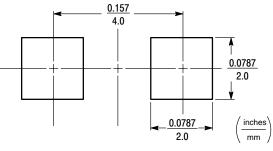


NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN MAX	
Α	0.160	0.180	4.06	4.57
В	0.090	0.115	2.29	2.92
С	0.075	0.095	1.91	2.41
D	0.050	0.064	1.27	1.63
Η	0.002	0.006	0.05	0.15
ſ	0.006	0.016	0.15	0.41
Κ	0.030	0.060	0.76	1.52
S	0.190	0.220	4.83	5.59







SMA FOOTPRINT

<u>Notes</u>

<u>Notes</u>

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